CC1350 RF

VDDS Decoupling Capacitors

Place L1 and C8 close to pin 33

R67, R68, R69 select source of power for RF switch; only mount one of them

Sub-1 GHz RF section

2.4 GHz RF section

CC1350 IO block placed on page 2.

L32, C71 and C23 for antenna matching

C24 and C59 for antenna matching
BoosterPack Headers and Peripherals

5V and 3V header

External flash

Jumpers M13-M14 to be mounted on header P6
XDS110 Debugger Interface

P10 selects the voltage source for the level shifters.
When powering CC1350 from the XDS supply, connect jumper between pins 1 and 2.
When powering CC1350 from the external supply, connect jumper between pins 2 and 3.

Jumpers M12 to be mounted between pins 1 and 2 on P10.

Jumpers M1-M11 to be mounted on header P4.

Use P5 for debugging CC1350 with an external debugger (requires that all jumpers on P4 be removed).

Use P7 for debugging external targets (requires that all jumpers on P4 be removed).

DIR = H: A -> B  
DIR = L: B -> A  
OE = H: output = Hi-Z  

XDS-RST = 0 -> output = 0  
XDS-RST = 1 -> output = Hi-Z  

TMS signal is bidirectional. TMS_DIR used to control direction of level shifter.
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